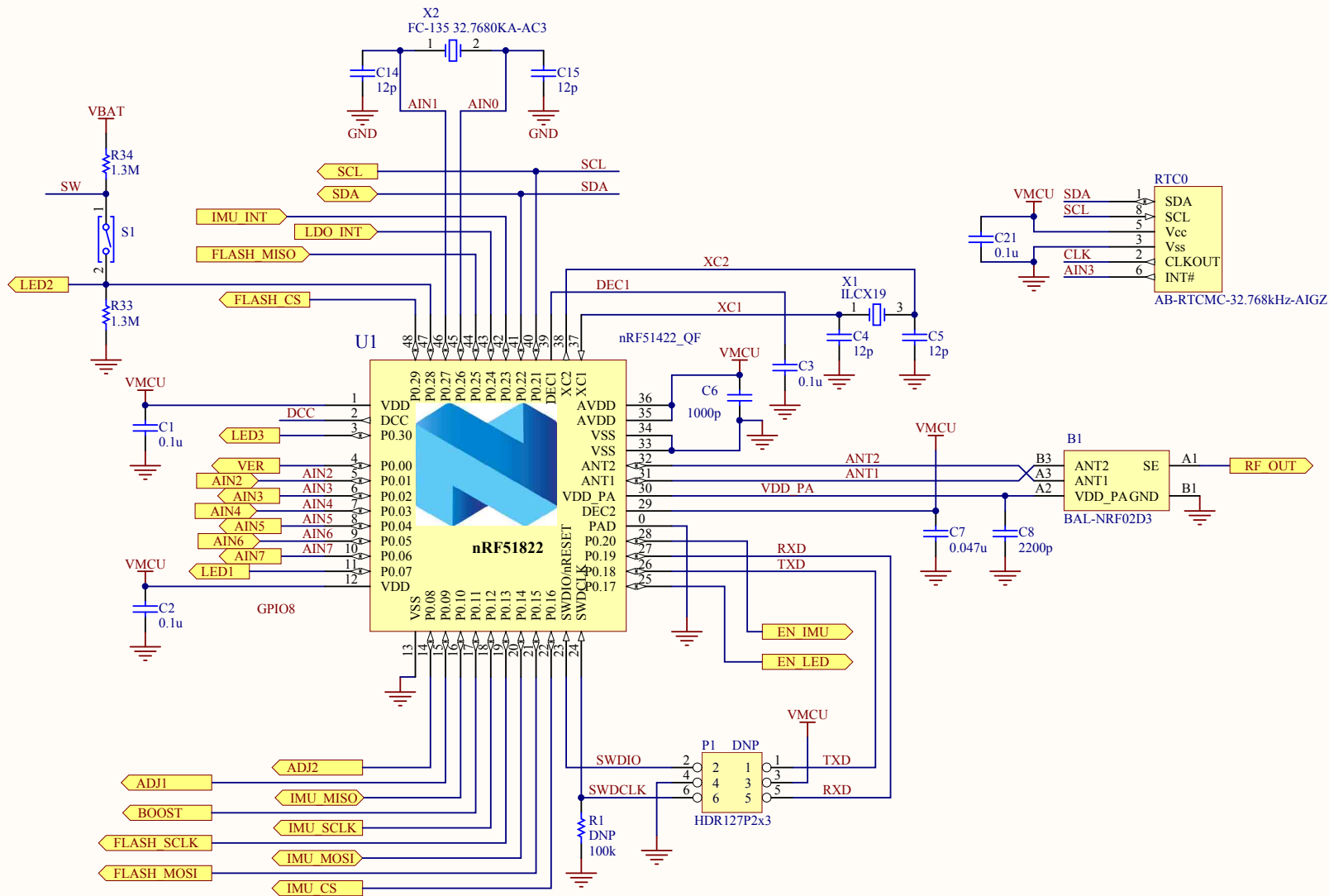


Hello		
TITLE Gas Gauge with LDO		REV EVT2
DATE 11/19/2014	DRAWN BY Dyke Shaffer	SHEET 2 OF 4





A

B

C

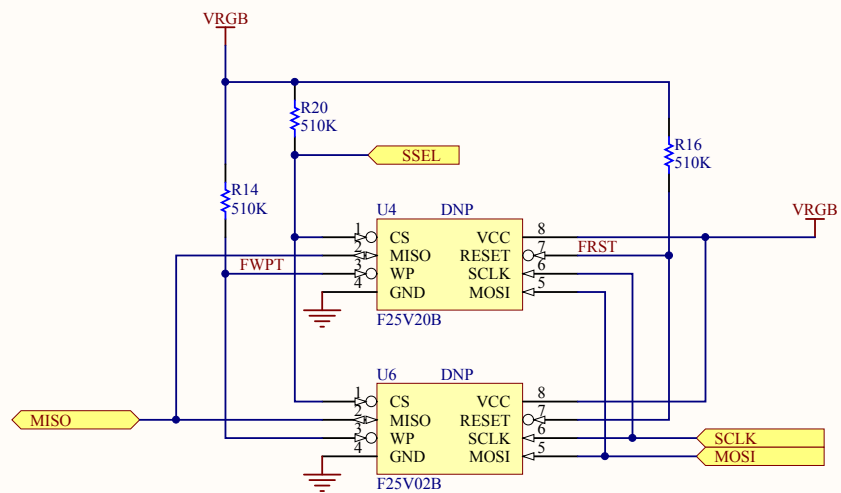
D

A

B

C

D



Hello		
TITLE Storage Sub-board		REV EVT2
DATE 11/19/2014	DRAWN BY John Kelley	SHEET 7 OF 8

FABRICATION NOTES

4 LAYER BOARD

- 1. Material to be CEM3, FR4, or MC3 @ .031" +/- .005" nominal thickness.
- 2. Finished copper thickness to be 1 oz.
- 3. All holes drilled from component side to meet IPC600 requirements for breakout. Hole size indicates finished diameter
- 4. All tooling hole centers to be within +/- .003" of center of datum hole
All other hole centers to be within +/- .005" of center datum hole
- 5. Trace width reduction due to etch factor, pits or dents is not to exceed .005"
- 6. Minimum annular ring to meet IPC600 requirements.
- 7. Apply silkscreen using white epoxy ink to component side, per artwork provided.
- 8. Apply soldermask over bare copper per artwork provided.
PC401 or SR1000 Green.
- 9. Boards must display manufacturers UL company ID (or Trademark) and type designator in copper or white epoxy ink.

+/-

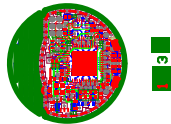
Symbol	Hit Count	Tool Size	Plated	Hole Type
□	109	12mil (0.305mm)	PTH	Round
○	4	22mil (0.559mm)	PTH	Round
▽	6	28mil (0.711mm)	PTH	Round
	119 Total	.XX .XXX ANGLES .01 .005		

dimensions are in inches
Tolerances are:

TOP Layer	Prepreg
GND Layer	Prepreg
SIG Layer	0.024 Core
BOT Layer	Prepreg

0.031 +- 0.005 mils

Top Side Component Designators



Unless otherwise specified

B: Add Voltage level shifting
D:make pin 8 of J2 go to chassis

SayHello
1660 17th St
San Francisco, CA 94105
(415) 000-0000

TITLE: FABRICATION DRAWING
Pill PCB Fab Drawing

DWG NO.: 000-00000	REV: A	ECO NO.:
DRAWN BY: Dyke Shaffer	DATE: 05.16.14	
SCALE: N/A	SHEET 1 OF 1	